TOSHIBA Field Effect Transistor Silicon P Channel MOS Type ( $L^2$ - $\pi$ -MOSV)

## **2SJ525**

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

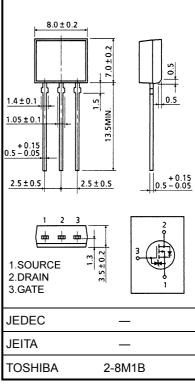
• Low drain–source ON resistance :  $R_{DS}$  (ON) = 0.1  $\Omega$  (typ.) • High forward transfer admittance :  $|Y_{fs}| = 4.5 \text{ S}$  (typ.) • Low leakage current :  $I_{DSS} = -100 \mu A$  (max) ( $V_{DS} = -30 V$ )

• Enhancement-mode :  $V_{th} = -0.8 \sim -2.0 \text{ V (VDS} = -10 \text{ V, ID} = -1 \text{ mA})$ 

## **Maximum Ratings (Ta = 25°C)**

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-30	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20 kΩ)	$V_{DGR}$	-30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	-5	Α	
Drain current	Pulse (Note 1)	I <sub>DP</sub>	-20	Α	
Drain power dissipation	n (Ta = 25°C)	P <sub>D</sub>	1.3	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	517	mJ	
Avalanche current		I <sub>AR</sub>	-5	Α	
Repetitive avalanche e	nergy (Note 3)	E <sub>AR</sub>	0.13	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	

## Unit: mm



Weight: 0.54 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	96.1	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = -25 V,  $T_{ch}$  = 25°C (initial), L = 14.84 mH,  $R_G$  = 25  $\Omega$ ,  $I_D$  = -5 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.

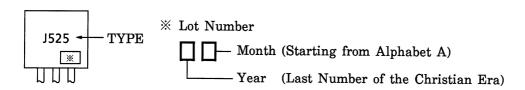
## **Electrical Characteristics (Ta = 25°C)**

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off cu	rent	I <sub>DSS</sub>	V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V	-	_	-100	μΑ
Drain-source br voltage	eakdown	V <sub>(BR) DSS</sub>	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V
Gate threshold v	roltage	$V_{th}$	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-source ON resistance		Pro (ou)	V <sub>GS</sub> = -4 V, I <sub>D</sub> = -2.5 A	_	0.17	0.2	Ω
		R <sub>DS</sub> (ON)	$V_{GS} = -10 \text{ V}, I_D = -2.5 \text{ A}$	_	0.1	0.12	
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -2.5 A	2.0	4.5	_	S
Input capacitano	е	C <sub>iss</sub>		_	850	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		250	_	pF
Output capacitance		Coss		-	330	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ $V_{GS}$ $V_{DD}$ $V_{DD}$ $V_{DD}$ $V_{DD}$	_	50	_	ns ns
	Turn-on time	t <sub>on</sub>		_	75	_	
	Fall time	t <sub>f</sub>		_	20	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\mathbf{W}} = 10 \mu \text{s}$		95	_	
Total gate charge (Gate-source plus gate-drain)		$Q_{g}$	V <sub>DD</sub> ≈ -24 V, V <sub>GS</sub> = -10 V,	_	27	_	
Gate-source charge		Q <sub>gs</sub>	$I_{D} = -5 A$		19	_	nC
Gate-drain ("miller") charge		$Q_{gd}$		_	8	_	

## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	-5	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	-20	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = -5 A, V <sub>GS</sub> = 0 V	_	_	1.7	V
Reverse recovery time		I <sub>DR</sub> = -5 A, V <sub>GS</sub> = 0 V	1	60	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 50 A / μs	_	56	_	nC

## Marking



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